

PATENT ASSIGNMENT COVER SHEET

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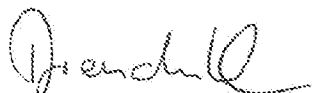
EPAS ID: PAT4855512

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
MICROSYSTEMS ON SILICON (PTY) LTD.	01/26/2018
RECEIVING PARTY DATA	
Name:	ELMOS SEMICONDUCTOR AKTIENGESELLSCHAFT
Street Address:	HEINRICH-HERTZ-STRASSE 1
City:	DORTMUND
State/Country:	GERMANY
Postal Code:	44227
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	10552129
CORRESPONDENCE DATA	
Fax Number:	(651)735-1102
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	651-735-1100
Email:	pairedocketing@ssiplaw.com
Correspondent Name:	SHUMAKER & SIEFFERT, P.A.
Address Line 1:	1625 RADIO DRIVE
Address Line 2:	SUITE 100
Address Line 4:	WOODBURY, MINNESOTA 55125
ATTORNEY DOCKET NUMBER:	1020-017US01
NAME OF SUBMITTER:	SHIRLEY A. BETLACH
SIGNATURE:	/Shirley A. Betlach/
DATE SIGNED:	03/07/2018
Total Attachments: 1	
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ASSIGNMENT

For valuable consideration, we, Microsystems on Silicon (PTY) Ltd., having a place of business at: 418 Mendelsohn Street, Waterkloof Glen, 0161, P.O. Box 73856, ZA-0040 Lynnwood Ridge, South Africa, hereby assign to: Elmos Semiconductor Aktiengesellschaft, having a place of business at: Heinrich-Hertz-Straße 1, 44227 Dortmund, Germany and its successors and assigns (collectively hereinafter called "the Assignee") the entire right, title and interest throughout the world in the inventions and improvements which are the subject of an application for United States Patent signed by us, entitled SENSING DEVICE FOR SENSING A PHYSICAL PARAMETER, filed August 31, 2006, and assigned U.S. Serial Number 10/552,129, issued on March 25, 2008 as U.S. Patent 7,348,561 B2; (hereinafter called "the application"), the application being a national stage application of PCT/EP2004/003666, filed April 6, 2004, which claims the benefit of South Africa application no. 2003/2684, filed April 7, 2003, this assignment including said application, any provisional, non-provisional, continuation, continuation-in-part, divisional, reissue, renewal, extension or other application for any of said inventions or improvements, any and all United States and foreign patents, utility models, and design registrations granted for any of said inventions or improvements, and the right to claim priority based on the filing date of said application under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes and we authorize the Assignee to apply in all countries in our name or in its own name for patents, utility models, design registrations and like rights of exclusion and for inventors' certificates for said inventions and improvements; and we agree for ourselves and our respective heirs, legal representatives and assigns, without further compensation to perform such lawful acts and to sign such further applications, assignments, Preliminary Statements and other lawful documents as the Assignee may reasonably request to effectuate fully this assignment, including any claims for damages by reason of past infringement or for provisional rights, and the right to sue for and collect on such claims for the Assignee's own use and benefit.

Date: 26. JAN. 2018



*** [Name and Title of Person Signing]
Microsystems on Silicon (PTY) Ltd.
418 Mendelsohn Street, Waterkloof Glen, 0161
P.O. Box 73856, ZA-0440 Lynnwood Ridge
South Africa

Date: 2018-01-24



*** [Name and Title of Person Signing]
Elmos Semiconductor Aktiengesellschaft
Heinrich-Hertz-Straße 1
44227 Dortmund
Germany

elmos^{AG}
Semiconductor AG
Heinrich-Hertz-Str. 1
44227 Dortmund